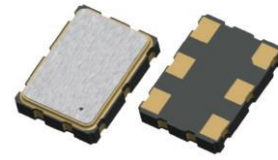


Features

- Typical 2.0 x 1.6 x 0.75 mm ceramic SMD package.
- low Power Supply Voltage: 3.3V, 2.5V, 1.8V
- Frequency 32.768kHz
- Singled-end Output:CMOS
- Frequency Stability ± 25 ppm over -40oC to 85oC @3days A
- Pb-free/RoHS compliant
- RTC Reference Clock
- Wearable device
- Sport Video Cams
- Mobile Phones
- Health and Wellness Monitors



BS2016A Series

Parameter		3.3v		2.5V		1.8V		Unit	Condtions
		Min.	Max.	Min.	Max.	Min.	Max.		
Supply Voltage Variation		VDD-10%	VDD+10%	VDD-5%	VDD+5%	VDD-5%	VDD+5%	V	
Frenquency		32.768						kHz	
Transition Time (10%-90%)	Rise Time / Fall Time	-	15.0	-	15.0	-	15.0	nSec	
Supply Current (No Load)		-	35	-	35	-	35	uA	@No Load
Duty Cycle		45	55	45	55	45	55	%	
Output Level		2.97	-	2.25	-	1.62	-	V	Output High
		-	0.33	-	0.25	-	0.18	V	Output Low
Tri-State Mode (Input to Pin 1)	Enable	0.7 x VDD	-	0.7 x VDD	-	0.7 x VDD	-	V	
	Disable	-	0.3 x VDD	-	0.3 x VDD	-	0.3 x VDD		
Stand by Current		-	3	-	3	-	3	uA	
Output Loading (CMOS)		-	15	-	15	-	15	pF	
Startup Time		-	20	-	20	-	20	mSec	
Aging		-	± 3	-	± 3	-	± 3	ppm	@ 25°C, First Year
Storage Temp. Range		-55	125	-55	125	-55	125	°C	
FREQ. STABILITY vs. TEMP. RANGE			± 20 ppm		± 25 ppm		± 50 ppm		
		-10~+60	Available		Available		Available		
		-20~+70	Available		Available		Available		
		-40~+85	Conditional		Available		Available		

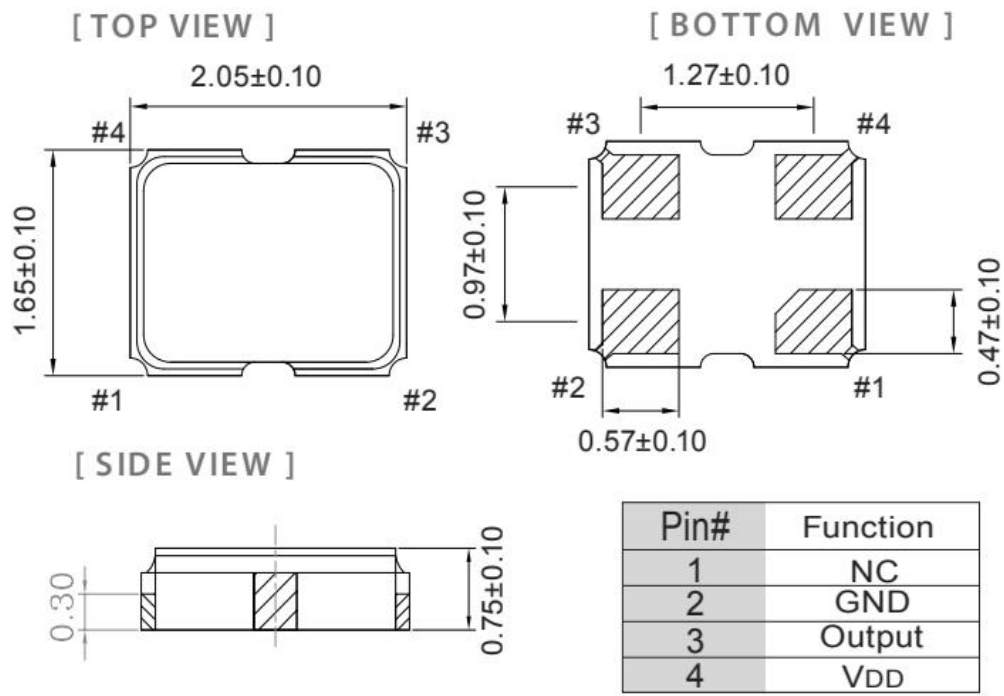
Note: not all combination of options are available. Other specifications may be available upon request.

Reliability

Parameter	Condition
Test	IEC60068, GJB360B
Mechanical Stress Test	IEC60068, GJB360B
EMC Test (ESD)	IEC61000, JESD22
Solderability	EIA/JESD22-B102-C
Contact Pads	Gold over Nickel
RoHS	RoHS Directive 2011/65/EU Annex II Recasting 2002/95/EC

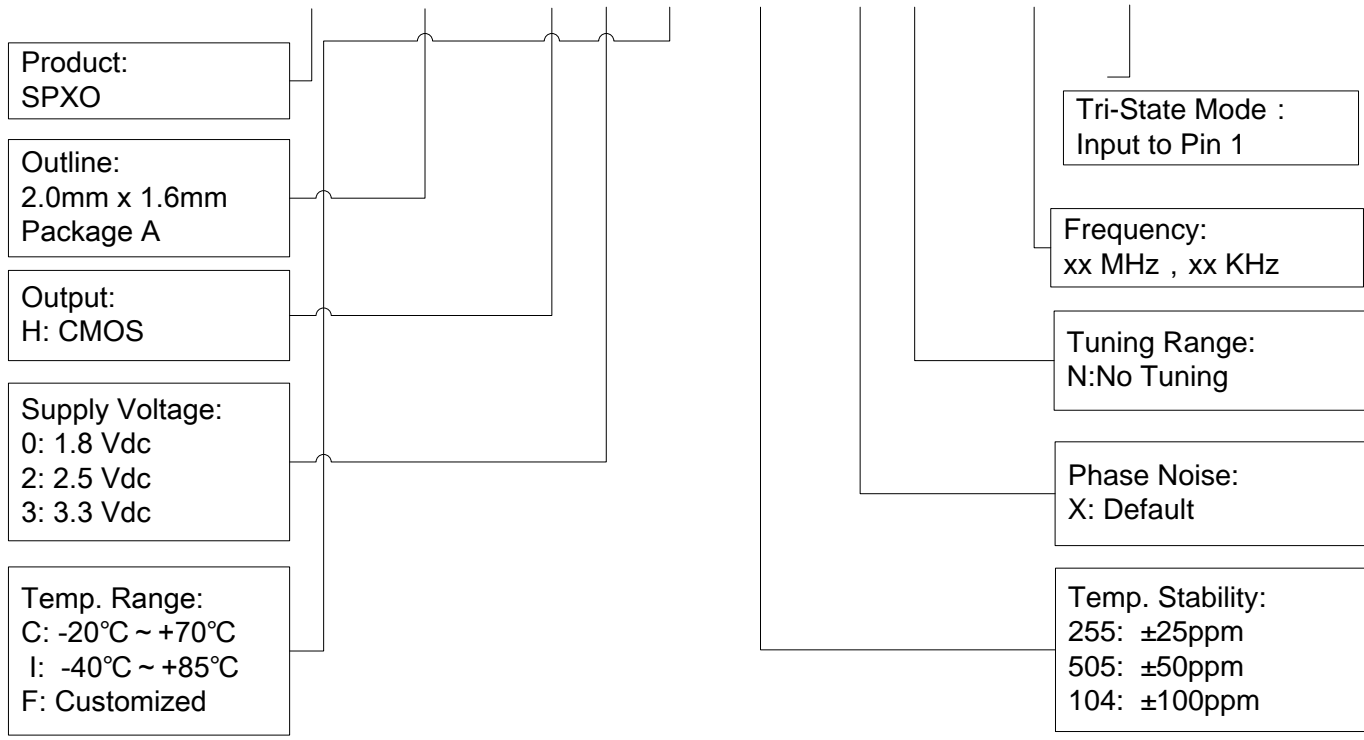
Outline Dimension & Pin Connections

Unit:
mm



Ordering Guide

BS2016A X X X XXX X XXX.XX X



Example: BS2016AD3I505CN20

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